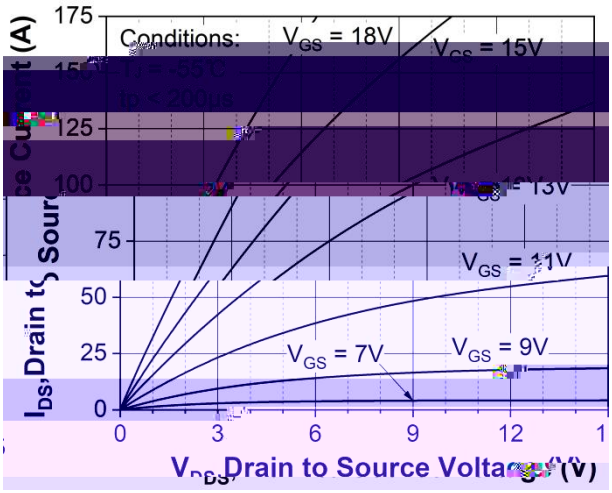


Figure 1. Output characteristics T_J = -55 ºC

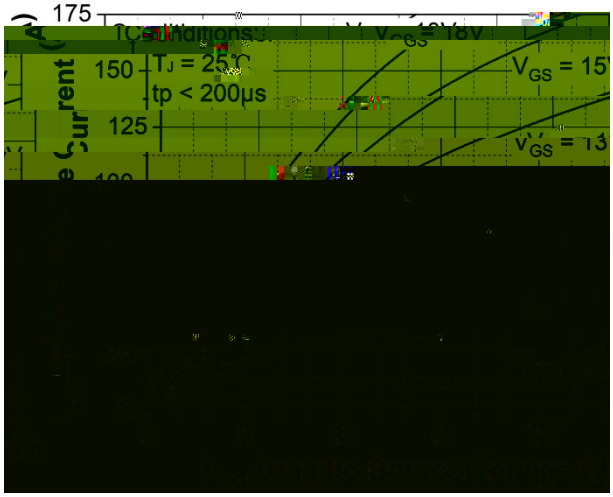


Figure 2. Output characteristics T_J = 25 ºC

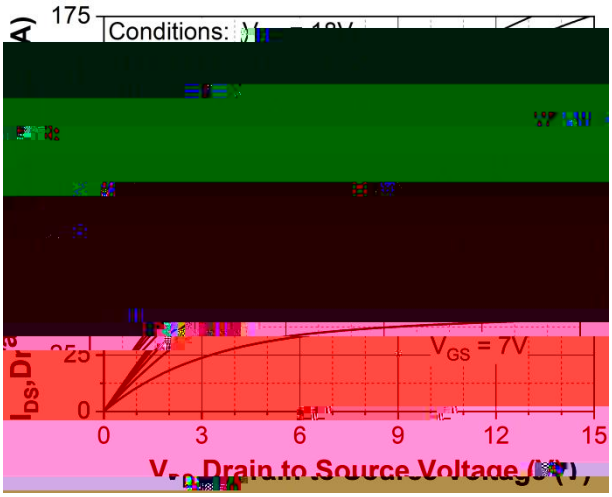


Figure 3. Output characteristics T_J = 175 ºC

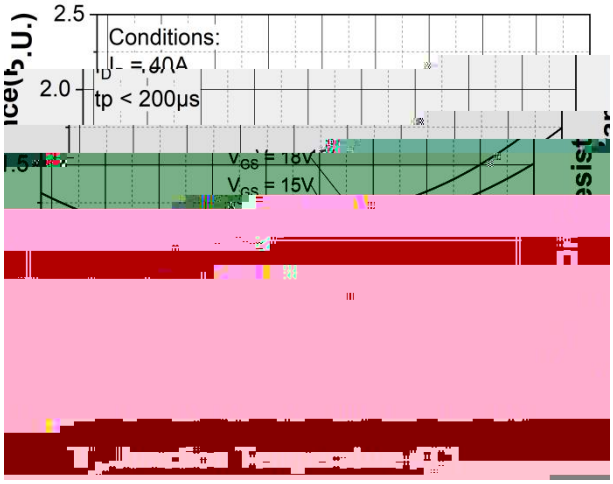


Figure 4. Normalized on-resistance vs. temperature

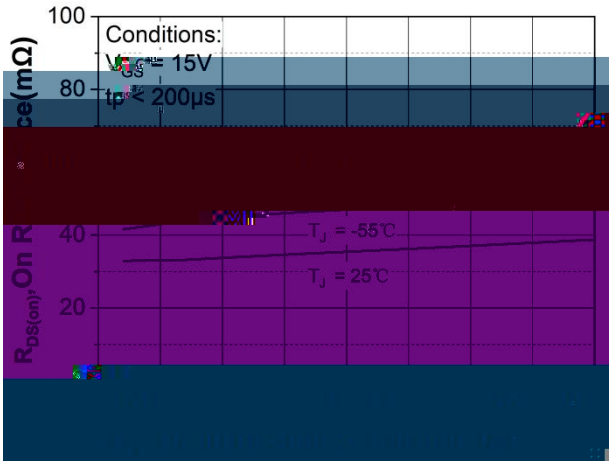


Figure 5. On-resistance vs. drain current
for various temperatures

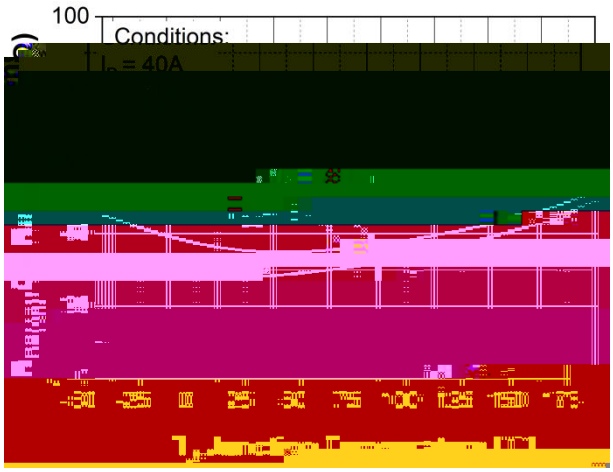


Figure 6. On-resistance vs. temperature
for various gate voltage

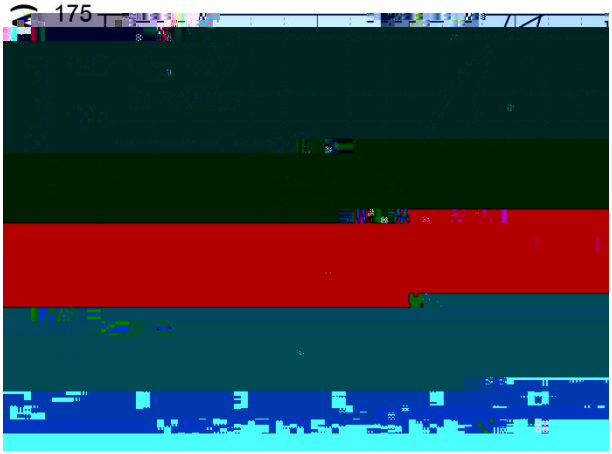


Figure 7. Transfer characteristic for various junction temperatures

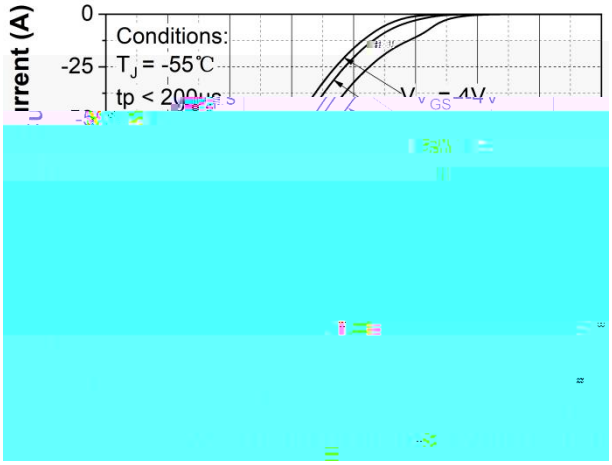


Figure 8. Body diode characteristic at T_J = -55 ºC

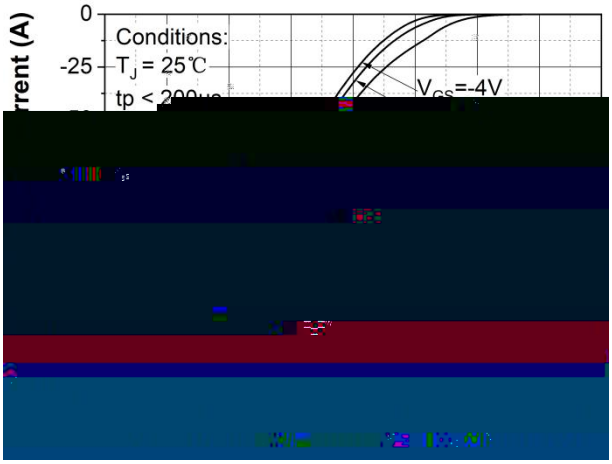


Figure 9. Body diode characteristic at T_J = 25 ºC

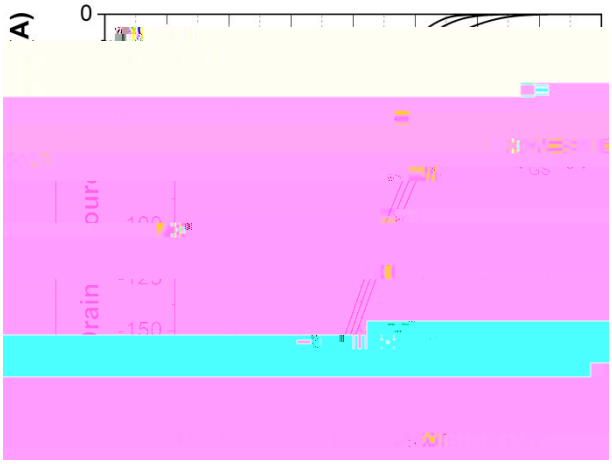


Figure 10. Body diode characteristic at T_J = 175ºC

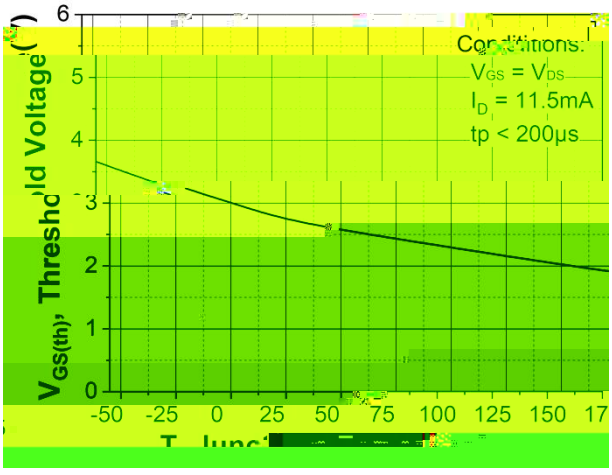


Figure 11. Threshold voltage vs. temperature

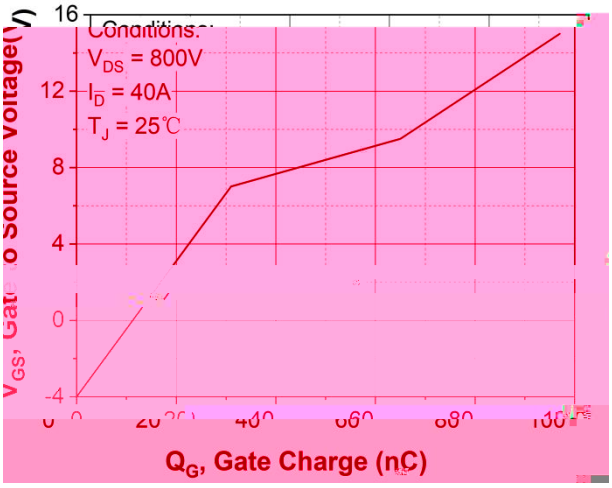


Figure 12. Gate charge characteristic

Die size W x L	4.986 * 3.74	mm	
Gate pad size W x L	0.8 * 0.8	mm	
Die thickness	200	μm	
Top side source gate metallization	4	μm	Ti/Al
Back side drain metallization	1	μm	Ti/Ni/Ag

Symbol	Dimension / mm
B	3.740
b1	0.800
b2	0.900
b3	0.950
b4	0.900
A	4.986
a1	0.800

—	—	—	—
—	—	—	—
—	—	—	—

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6. Due to technical requirements products may contain dangerous substances. For information on the types in question please contact Sichain office.

7. Except as otherwise explicitly approved by Sichain in a written document signed by authorized representatives of Sichain, Sichain' products may not be used in any applications where a failure of the product or any consequences of the use thereof can reasonably be expected to result in personal injury.

8. For use of our products in applications requiring a high degree of reliability (as exemplified below), please contact and consult with a Sichain representatives, for example but not limited to: transportation equipment,primary communication equipment,traffic lights,fire/crime prevention, safety equipment, medical systems, and power transmission systems.